[DESCRIPTION]

[Title of the Invention]

METAL RECOVERY SYSTEM

[Technical Field]

[0001]

The present invention relates to a metal detector.

[Background Art]

[0002]

Printed circuit boards used in the field of electronic components are configured from copper, which serves as the circuit, and resin, which serves as the substrate material. When forming an electroless plating film such as electroless copper plating on a printed circuit board, because there is a non-conductive material part on the surface of the printed circuit board to be plated, the application of a catalyst metal is required. In the catalytic process of applying the catalyst metal, the printed circuit board is treated in an alkaline catalyst metal ion solution and thereafter treated in a reducing agent solution, or treated in an acidic catalyst metal colloid solution and thereafter treated in an acid solution. Palladium is often used as the catalyst metal. The catalyst solution is replaced regularly. Valuable metals such as palladium contained in the spent catalyst solution are generally recovered using an adsorbent.

[Prior Art Documents]

[Patent Documents]

[0003]

[Patent Document 1] Japanese Unexamined Patent Application Publication No. 2013-205074

[Patent Document 2] Japanese Unexamined Patent Application Publication No. 2011-122987

[Patent Document 3] Japanese Unexamined Patent Application Publication No. 2000-107507

[Patent Document 4] Japanese Unexamined Patent Application Publication No. 2005-351784

[Patent Document 5] Japanese Patent No. 3019938

[Patent Document 6] Japanese Patent No. 3693124

[Patent Document 7] Japanese Patent No. 4410586

[Summary of the Invention]